

ABSTRACT

One aspect of the present disclosure is a manufacturing method for a support piece used in the formation of a dolmen structure in a semiconductor device, including steps of: (A) preparing a laminate film including a base material film, an adhesive layer, and a support piece formation film, for example, including a thermosetting resin layer, in this order; (B) forming a plurality of support pieces on a surface of the adhesive layer by singulating the support piece formation film; and (C) picking up the support piece in a state in which the support piece is thrust up from the base material film side by a plurality of needles or a member having a flat tip surface.

FIG. 7